

ABSTRACT

Methods and device for a probe card in the form of a multi-beam probe card that includes one or more beam assemblies disposed across an opening in a head plate. The probe card has a plurality of probe needles extending through the beam assemblies that provide for wide area coverage of a wafer undergoing test prior to cutting the wafer into individual chips. The multi-beam probe card may be used in a wafer test system that is configured to send test signals to the wafer and to evaluate the signal upon return.